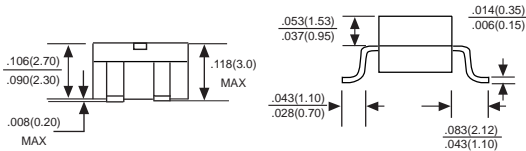
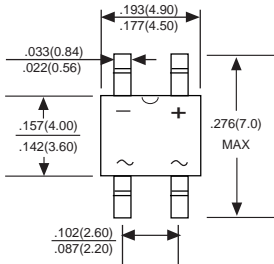


RMB2S THRU RMB10S

GLASS PASSIVATED FAST RECOVERY BRIDGE RECTIFIERS

Voltage Range - 200 to 1000 Volts Current - 0.5/0.8 Ampere

MBS



Dimensions in inches and (millimeters)

FEATURES

- ◆ Ideal for printed circuit board
- ◆ Reliable low cost construction utilizing molded plastic technique
- ◆ High temperature soldering guaranteed: 260°C/10 seconds at 5 lbs., (2.3kg) tension
- ◆ Small size, simple installation
- ◆ Leads solderable per MIL-STD-202, Method 208
- ◆ High surge current capability
- ◆ Glass passivated chip junction
- ◆ Green compound(halogen&Sb₂O₃ free)

MECHANICAL DATA

Case: Molded plastic body

Terminals: Plated leads solderable per MIL-STD-750, Method 2026

Polarity: Polarity symbols marked on case

Mounting Position: Any

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load derate current by 20%.

	SYMBOLS	RMB2S	RMB4S	RMB6S	RMB8S	RMB10S	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Maximum average forward rectified current							
On glass-epoxy P.C.B.(Note1)	$I_{F(AV)}$			0.5			A
On aluminum substrate(Note2)				0.8			
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}			30			A
Maximum instantaneous forward voltage drop per leg at 0.4A	V_F			1.3			V
Maximum DC reverse current					5.0		uA
at rated DC blocking voltage	I_R			500			uA
Typical thermal resistance(NOTE 3)	$R_{\theta JL}$			28			°C/W
	$R_{\theta JA}$			85			
Maximum reverse recovery time (NOTE 4)	t_{rr}	150		250	500		ns
Operating temperature range	T_J			-55 to +150			°C
storage temperature range	T_{STG}			-55 to +150			°C

NOTES:1.On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads.

2.On aluminum substrate P.C.B. with an area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad.

3.Thermal resistance form junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.

4.Reverse recovery condition $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$.

RATINGS AND CHARACTERISTIC CURVES RMB2S THRU RMB10S

FIG.1 FORWARD DERATING CURVE

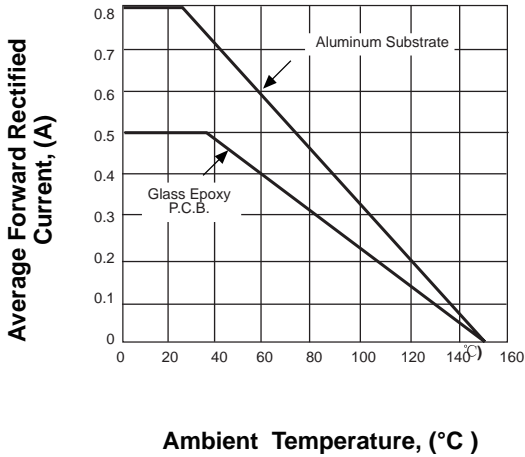


FIG.2 PEAK FORWARD SURGE CURRENT

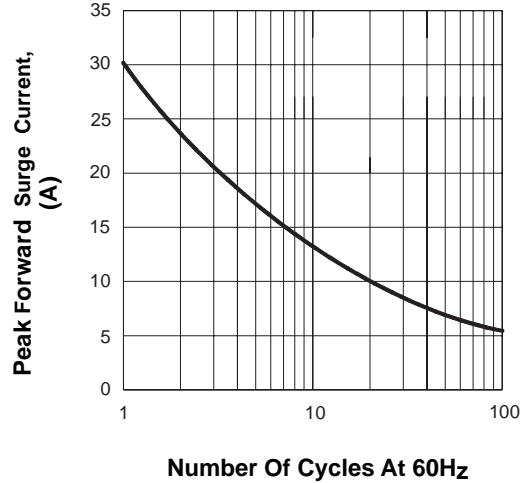


FIG.3 TYPICAL FORWARD CHARACTERISTICS

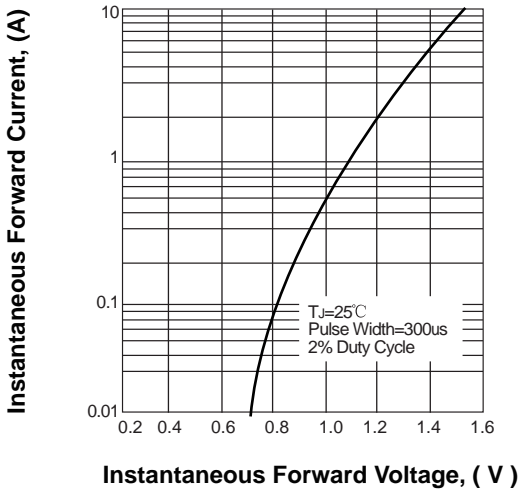


FIG.4 TYPICAL REVERSE CHARACTERISTICS

